

lines 7-10, delete in their entirety and  
substitute therefor --instance, this can be  
achieved by exerting the actuating force tending  
toward the center of the wafer upon the wafer  
peripheral edge,

Page 14, line 17, after "invention," insert --there is  
provided a wafer holding device adapted for use in  
an apparatus for treating a principal surface of a  
semiconductor wafer under a predetermined heating  
condition while the back surface of said principal  
surface of the wafer is vertically or obliquely  
held by the device at the predetermined position  
within a chamber of said apparatus. The device  
comprises a substrate holder for supporting the  
back surface of said wafer thereon and rotating  
means for circumferentially rotating said wafer  
along with the substrate holder.--;  
line 18, change "the" to --~~the~~--.

IN THE CLAIMS:

Please amend claim 5 as follows:

5. (Amended) A wafer holding device adapted for us in an  
apparatus for treating a principal surface of a semiconductor  
wafer under a predetermined heating condition while the back  
surface of said principal surface of the wafer is vertically or